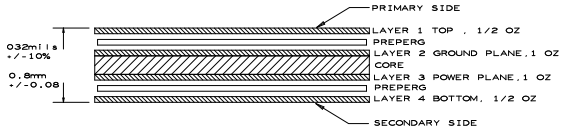
REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
1	PROTO RELEASE	16/11/15	RAJA
2	ALPHA RELEASE	11/12/15	RAJA

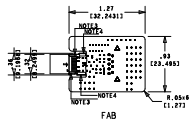


NOTE: 8 MIL 6 MIL SPACING TRACES ON LAYER 1 DIFFERENTIAL IMPEDANCE CONTROLLED TO 90 OHMS +/- 10% TESTED

NOTE: 8 MIL 6 MIL SPACING TRACES ON LAYER 4 DIFFERENTIAL IMPEDANCE CONTROLLED TO 90 OHMS +/- 10% TESTED

NOTES:(UNLESS OTHERWISE SPECIFIED)

1. RoHS COMPLIANT CERTIFICATION OR MATERIAL DECLARATION REQUIRED.
2. MATERIAL:
   A. IS410 OR EQUIVALENT. MATERIAL MUST CONFORM TO UL94V-0.
   B. USE HTE COPPER, AS SPECIFIED IN THE CROSS SECTION DIAGRAM.
   C. OVERALL METAL TO METAL THICKNESS AS SPECIFIED IN THE CROSS SECTION.
3. DRILLING:
   A. DIAMETERS IN DRILL TABLE ARE FINISHED HOLE SIZES +/-.003 tol.
      UNLESS OTHERWISE SPECIFIED IN DRILL TABLE.
   B. TEARDROP ALLOWED ON ENTRY OF VIA ON EVERY TRACE LAYER.
4. PLATING:
      COPPER PLATING IN THRU-HOLES .001 min.
5. MARKING:
   A. SILKSCREEN IN WHITE NON-CONDUCTIVE EPOXY INK ON PRIMARY SIDE OF THE BOARD OR BOTH SIDES IF APPLICABLE.
   B. FABRICATOR TO PLACE DATE CODE, LOGO AND RoHS COMPILANT SYMBOL IN SILKSCREEN ON SECONDARY SIDE.
6. FINAL FABRICATION:
   A. SOLDRMASK PRIMARY AND SECONDARY SIDE OF BOARD USING LIQUID PHOTOIMAGABLE MASK MATERIAL OVER BARE COPPER. PER IPC-SM-840. MASK ARTWORKS PROVIDED ARE 1:1. SOLDERMASK COLOR **BLUE**
7. FINISH:
   A. SHALL BE ELECTROLESS NIKEL / IMMERSION GOLD(ENIG).
   B. NICKEL THICKNESS: 100-200 MICROINCHES.
   C. GOLD THICKNESS: 3-10 MICROINCHES.
8. BOARDS SHALL BE PURCHASED FROM UL RECOGNIZED VENDORS ONLY. FLAMABILITY RATING (94-VO).
9. MANUFACTURE BOARD TO BE IN ACCORDANCE WITH PERFORMANCE STANDARD IPC-6011/6012 CLASS 2 BOARD TO BE INSPECTED PER IPC-600-A CLASS 2.
10. MAXIMUM WRAP OR TWIST SHALL NOT EXCEED .007 in/in.
11. TESTING:
   A. FABRICATOR TO ADD TEST STRUCTURES OR CUPONS AS NEEDED.
   B. T-LINE IMPEDENCE TO BE TESTED OR GUARANTEE WITHIN 10% IF SPECIFIED IN THE CROSS SECTION. TOLERANCE TO BE +/-10% UNLESS OTHERWISE SPECIFIED.



FAB

DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
-	10.0	+3.0/-3.0	PLATED	98
*	30.06	+3.0/-3.0	PLATED	9
△	91.0	+3.0/-3.0	PLATED	2

USB TYPE-C CONNECTOR



NOTE 1 FINE PITCH COMPONENT 0.5mm PITCH
NOTE 2 PCB PADS CONFIGURATION BE SAME BETWEEN A SIDE AND B SIDE
NOTE 3 THESE PADS ARE WHERE A CONNECTOR HOLDS PCB. SHALL NOT BE ELECTRICAL USE NOR SOLDERED
NOTE 4 RECOMMEND TO UTILIZE THE SIDE SHELL TABS OF TYPE-C PLUG BY SOLDERING TO PCB PADS FOR THE MECHANICAL STRENGTH
NOTE 5 WHILE ASSEMBILNG J1 MATCH THE NOTCH IN THE CONNECTOR WITH TRIANGLE IN THE SILK.

UNLESS OTHERWISE SPECIFIED	SIGNATURES		DATE
DIMENSIONS ARE IN INCHES	DRAWN :	HUSAIN	11/12/15
TOLERANCES ON: ANGLES +/- 2°	CHECKED :	RAJA	11/12/15
2 PL DECIMALS +/- .010	ENGRG :	RAGO	11/12/15
3 PL DECIMALS +/- .005	ISSUED		
THIRD ANGLE PROJECTIONS			

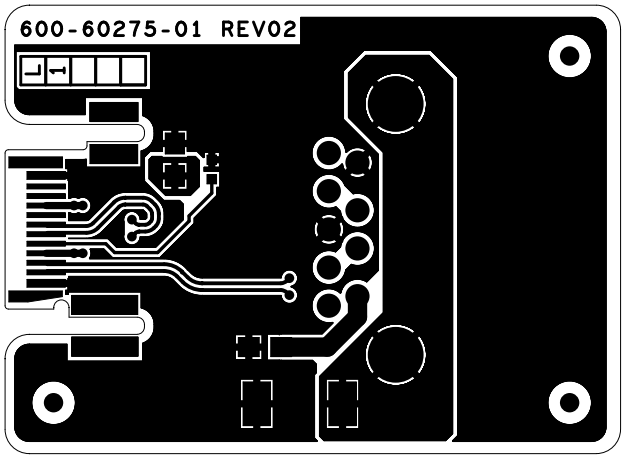
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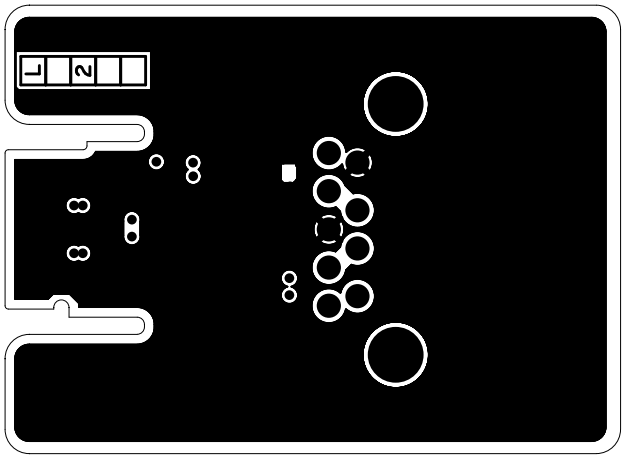
FABRICATION DRAWING TYPE-C TO TYPE-A ADAPTOR BOARD

SIZE	FSCM NO	DWG NO	REV
C		610-60277-01	02

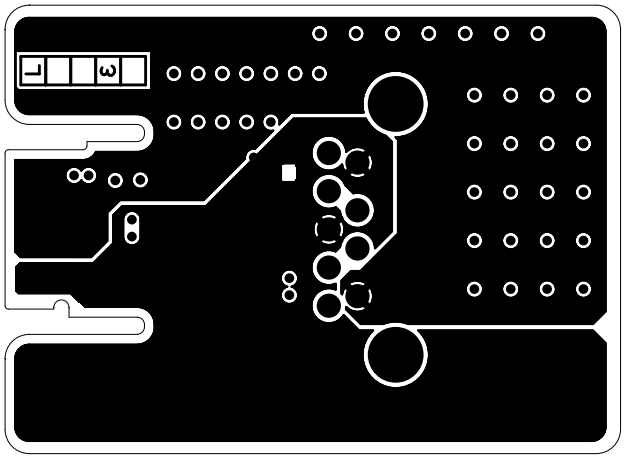
SCALE: 1/1 SHEET: 1 OF 1



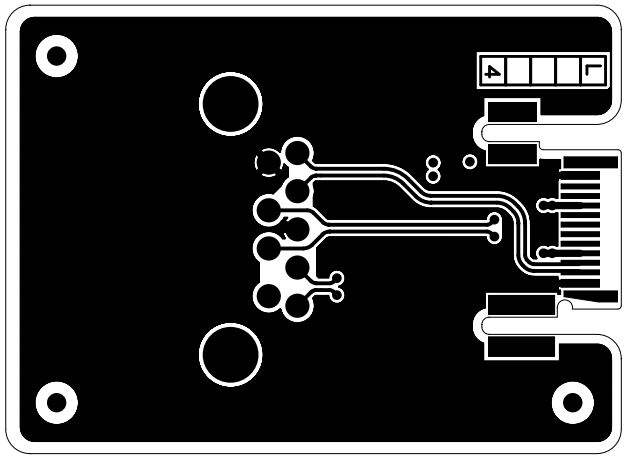
600-60275-01 REV02 PRIMARY SIDE



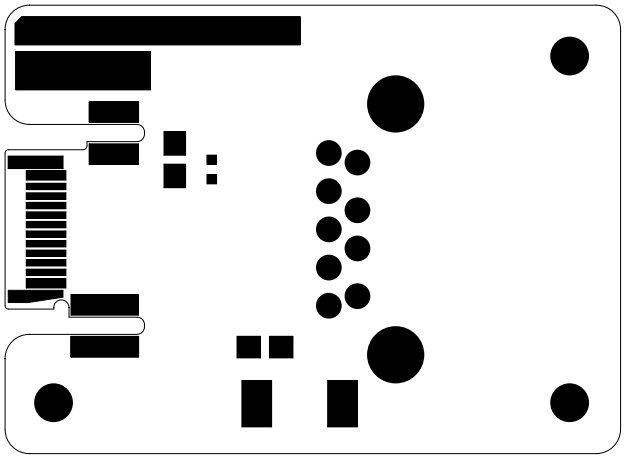
600-60275-01 REV02 GROUND1 LAYER



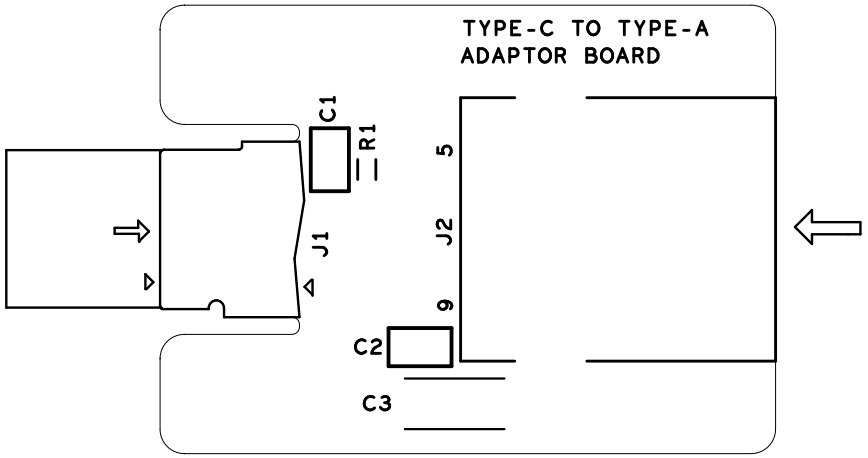
600-60275-01 REV02 POWER1 LAYER



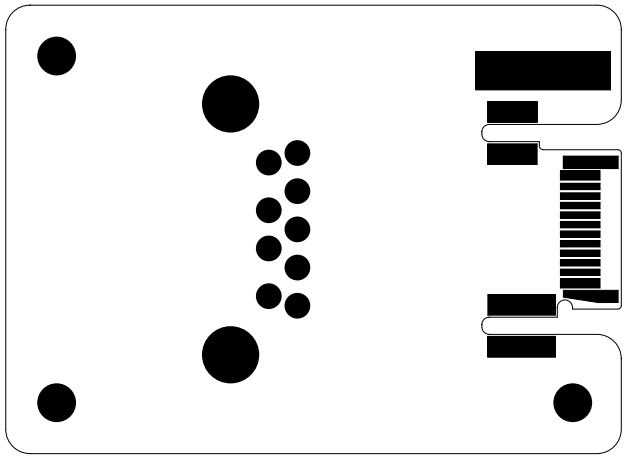
600-60275-01 REV02 SECONDARY SIDE



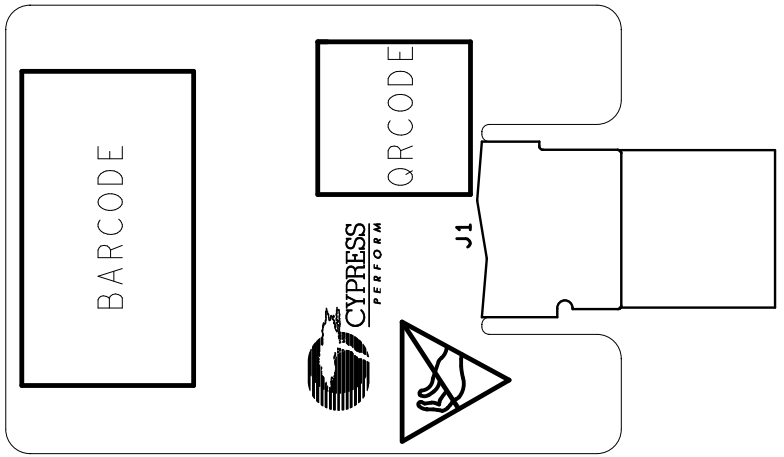
600-60275-01 REV02 PRIMARY SOLDERMASK



600-60275-01 REV02 PRIMARY SILKSCREEN



600-60275-01 REV02 SECONDARY SOLDER MASK



600-60275-01 REV02 SECONDARY SILKSCREEN